

June 2012: Packaging & Interconnects

Laser bar series touts high efficiency at 200 Watts continuous optical output power > 10

LED driver is compatible with traditional TRIAC dimming, analog dimming designs > 30

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Smart Grid & Alternative Energy

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The June 2012 issue of ECN deals with Packages & Interconnects. Technical

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Contributor, Jon Titus, continues his “Tips Help Engineers Write Well” series, while Executive Editor Chris Warner reviews “The Idea Factory.” The Brainstorm Q&A section asks “How will software play a role in the development of advanced technology vehicles and/or next-gen aircraft systems?”

Check it out [here](#) [1].

Summary:

The June 2012 issue of ECN deals with Packages & Interconnects. Technical Contributor, Jon Titus, continues his “Tips Help Engineers Write Well” series, while Executive Editor Chris Warner reviews “The Idea Factory.” The Brainstorm Q&A section asks “How will software play a role in the development of advanced technology vehicles and/or next-gen aircraft systems?”

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